

ENSC Batch No. _____ Wafers Started _____ Date _____
 Material _____ Orientation _____ Size _____ Thickness _____
 Resistivity _____ Type _____
 Wafer Vendor _____ Vendor Batch # _____ SFU P.O. _____

Process Step #	Process Conditions	Oper & Wafer #	Comments
			Note that all wafers normally must receive a thorough RCA clean per spec immediately prior to being placed in the furnace. In this case, this can be omitted if the wafers go straight from diffusion to LTO.
_____A	Prepare Furnace (Tube 1) N2 flow 4 scfh. O2 at 0. Fill bubbler with DI H2O. Ramp temp to 750C. Turn on bubbler and tapes.		
_____B	Load Wafers into Boat Use correct boat and white elephant. Use wafer forceps.		
_____C	Push Boat into Furnace Temp = 750C. Use gloves and quartz rod. Max push rate 4 in/min. N2 at 4 scfh		
_____D	Oxidation Furnace at temp. N2 at 4 scfh. O2 at about 0.5 scfh, for good bubbling action in bubbler. Open stopcock.		Time = 30 -45 min. Temp = 750C
_____E	Ramp Furnace Down Close stopcock. Set temp to 400C. N2 at 4 scfh. O2 at 0 scfh. Bubbler and tapes off.		
_____F	Pull Boat and Unload Pull out (< 4 in/min) when all zones <750C.		
_____G	Return Furnace to Idle O2 off. N2 at 0.5-1.0 scfh. Close O2 bottle valve.		
_____H	Inspect Colour, ellipsometer, etc.		